

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Appln. of:	<b>Uwe SCHWARZ</b>	Group Art Unit:	<b>2812</b>
Serial No.:	<b>10/537,211</b>	Conf. No.:	<b>1865</b>
Filed:	<b>March 20, 2006</b>	Examiner:	<b>Reema PATEL</b>
For:	<b>PRODUCTION OF MICROELECTROMECHANICAL SYSTEMS (MEMS) USING THE HIGH-TEMPERATURE SILICON FUSION BONDING OF WAFERS</b>	Atty Docket No.:	<b>D4695-00135</b>

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sirs:

Applicant submits this Supplemental Information Disclosure Statement pursuant to 37 C.F.R. §1.56. U.S. Patent No. 6,012,336 was first cited in a parallel European application. The required fee of \$180.00 charged to Deposit Account 04-1679 (Atty Docket No. D4695-00135) is submitted herewith via EFS charge authorization.

Respectfully submitted,

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